



# **Complementary Low-Threshold MOSFET Pair**

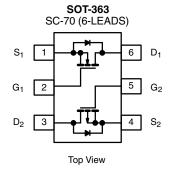
PRODUCT SUMMARY						
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)			
N-Channel	20	$0.385$ at $V_{GS} = 4.5 \text{ V}$	0.70			
		0.630 at V <sub>GS</sub> = 2.5 V	0.54			
P-Channel	- 8	0.600 at V <sub>GS</sub> = - 4.5 V	- 0.60			
		0.850 at V <sub>GS</sub> = - 2.5 V	- 0.50			
		1.200 at V <sub>GS</sub> = - 1.8 V	- 0.42			

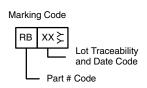
#### **FEATURES**

- TrenchFET® Power MOSFET
- Material categorization: For definitions of compliance please see www.vishav.com/doc?99912



HALOGEN FREE





Ordering Information: Si1555DL-T1-GE3 (Lead (Pb)-free and Halogen-free)

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)								
Parameter		Symbol	N-Channel		P-Channel			
			5 s	Steady State	5 s	Steady State	Unit	
Drain-Source Voltage		$V_{DS}$	20		- 8		V	
Gate-Source Voltage		$V_{GS}$	± 12		± 8		V	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	± 0.70	± 0.66	- 0.60	- 0.57	_	
	T <sub>A</sub> = 85 °C		± 0.50	± 0.48	- 0.43	- 0.41		
Pulsed Drain Current		I <sub>DM</sub>	±1				A	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	0.25	0.23	- 0.25	- 0.23		
	T <sub>A</sub> = 25 °C	В	0.30	0.27	0.30	0.27	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 85 °C	P <sub>D</sub>	0.16	0.14	0.16	0.14		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 5 s	R <sub>thJA</sub>	360	415			
	Steady State		400	460	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	300	350			

a. Surface mounted on 1" x 1" FR4 board.

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<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)									
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit			
Static									
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	0.6		1.4	V		
		$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 0.45		- 1	•		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	N-Ch			± 100	nA		
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	P-Ch			± 100			
Zero Gate Voltage Drain Current	L	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch			1			
		$V_{DS} = -8 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch			- 1	μΑ		
	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$				5	μΑ		
		V <sub>DS</sub> = -8 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C	P-Ch			- 5			
On-State Drain Current <sup>a</sup>		$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	N-Ch 1					
	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	P-Ch	- 1			Α		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 0.66 \text{ A}$	N-Ch	0.320 0.		0.385	;		
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 0.57 A	P-Ch		0.510	0.600	Ω		
		V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 0.40 A	N-Ch		0.560	0.630			
		V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 0.48 A	P-Ch		0.720	0.850			
		V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.20 A	P-Ch		1.000	1.200	1		
	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.66 A	N-Ch		1.5				
Forward Transconductance <sup>a</sup>		V <sub>DS</sub> = - 4 V, I <sub>D</sub> = - 0.57 A	P-Ch		1.2		S		
_	V <sub>SD</sub>	I <sub>S</sub> = 0.23 A, V <sub>GS</sub> = 0 V	N-Ch		0.8	1.2			
Diode Forward Voltage <sup>a</sup>		I <sub>S</sub> = - 0.23 A, V <sub>GS</sub> = 0 V	P-Ch		- 0.8	- 1.2	V		
Dynamic <sup>b</sup>									
•			N-Ch		0.8	1.2			
Total Gate Charge	$Q_g$	N-Channel	P-Ch		1.5	2.3	nC		
Gate-Source Charge	Q <sub>as</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 0.66 \text{ A}$	N-Ch		0.06				
date doubte charge	₩gs	P-Channel	P-Ch		0.17				
Gate-Drain Charge	Q <sub>gd</sub>	$V_{DS} = -4 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.57 \text{ A}$	N-Ch		0.30				
			P-Ch		0.16				
Turn-On Delay Time  Rise Time	t <sub>d(on)</sub>	N-Channel $V_{DD} = 10 \text{ V, R}_{L} = 20 \Omega$	N-Ch P-Ch		10	20			
			N-Ch		6 16	12 30			
		$I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$	P-Ch		25	50 50			
Turn-Off Delay Time	t <sub>d(off)</sub>		N-Ch		10	20	1		
		P-Channel $V_{DD} = -4 \text{ V, R}_{L} = 8 \Omega$	P-Ch		10	20	ns		
Fall Time	t <sub>f</sub>	$I_D \cong -0.5 \text{ A, } V_{GEN} = -4.5 \text{ V, } R_q = 6 \Omega$	N-Ch		10	20	1		
		J GEN / 9	P-Ch		10	20			
Source Drain Powerse Becovery Time	+	I <sub>F</sub> = 0.23 A, dl/dt = 100 A/μs			20	40			
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 0.23 A, dl/dt = 100 A/μs	P-Ch		20	40			

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

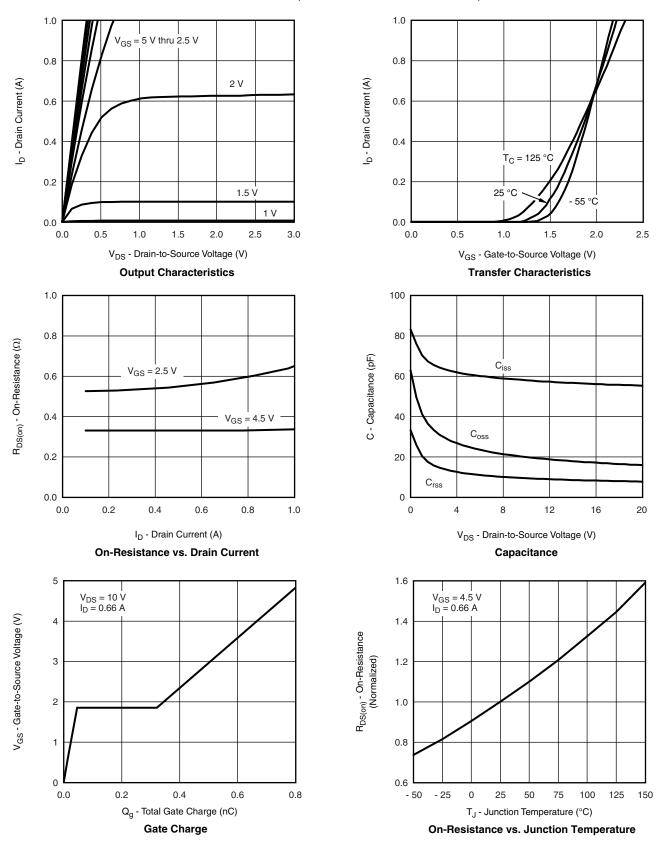
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.





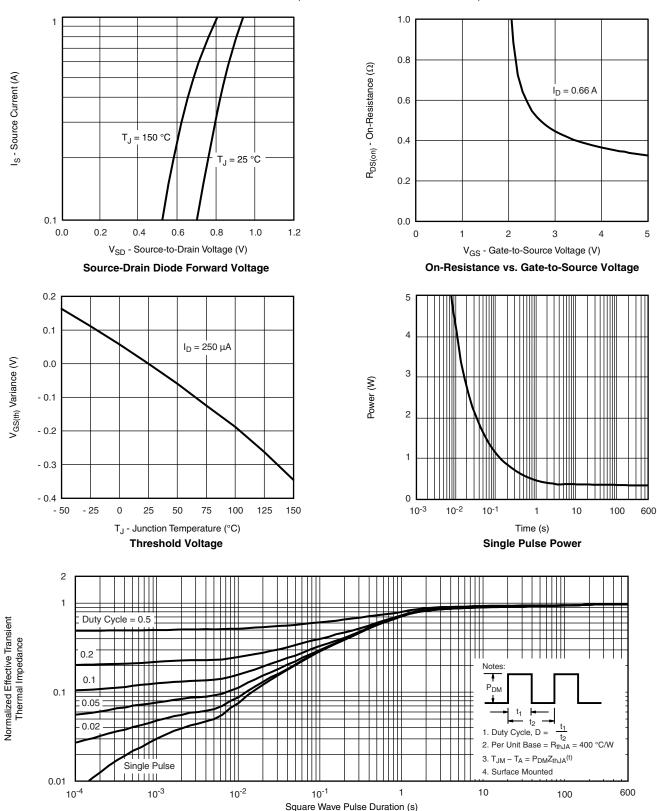
#### N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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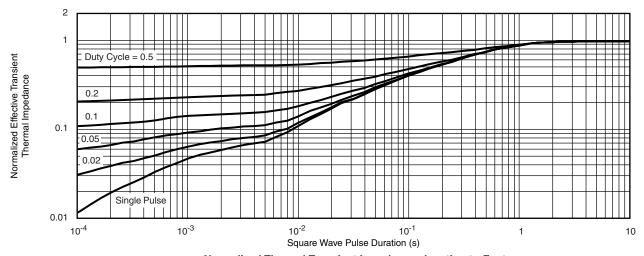


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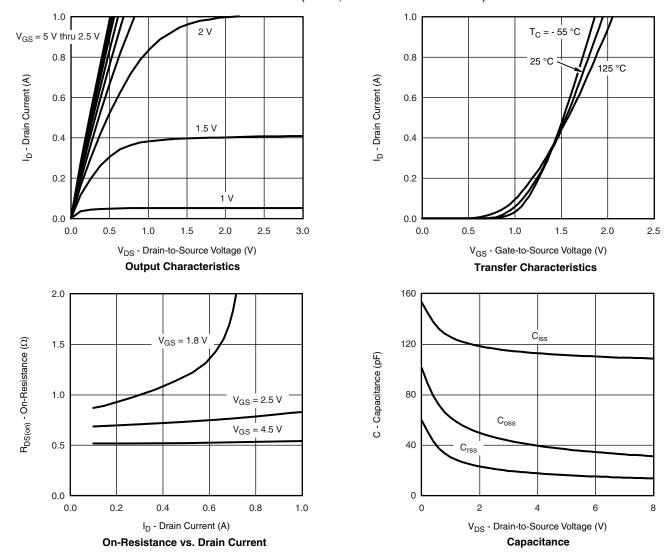


#### N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

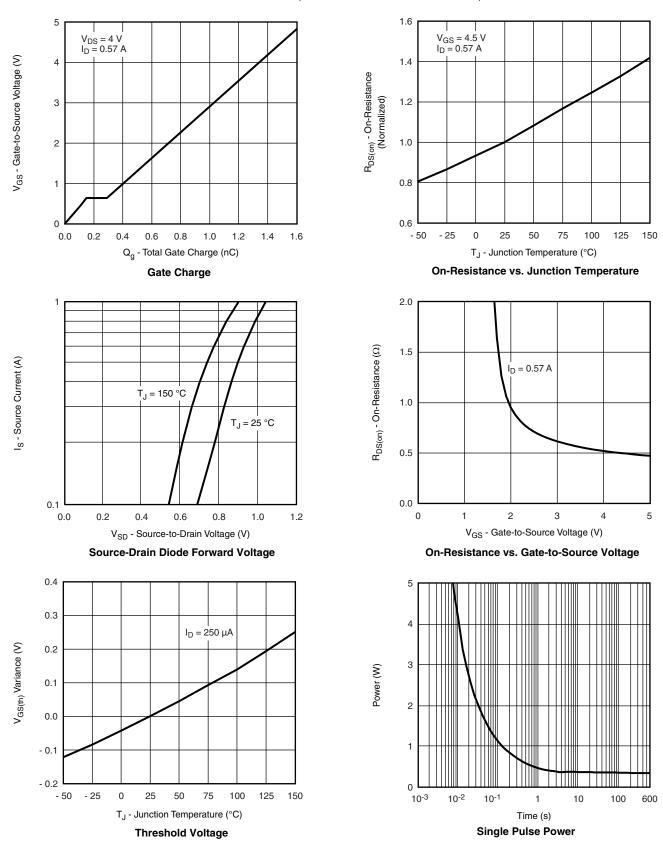
#### P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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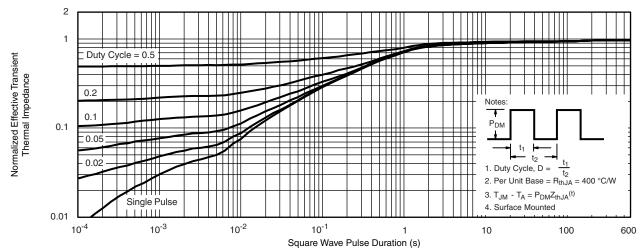


#### P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

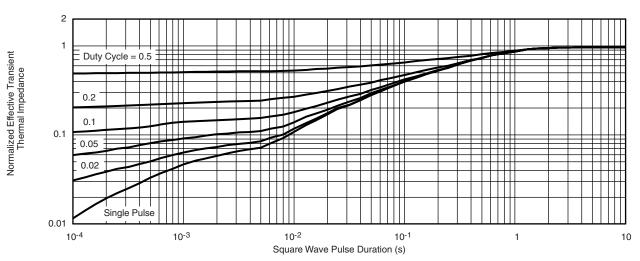




#### P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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Document Number: 71079 S13-0631-Rev. F, 25-Mar-13 For technical questions, contact: pmostechsupport@vishav.com



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